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प्लाज़्मा अनुसंधान संस्थान  
INSTITUTE FOR PLASMA RESEARCH  
परमाणु ऊर्जा विभाग, भारत सरकार का एक सहायता



प्राप्त संस्थान  
An Aided Institute of Department of Atomic Energy,  
Government of India

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दूरभाष: (079) 2396 2020/2021/2028  
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### ENQUIRY

ENQUIRY NO : IPR/EQL/19-20/013  
Date : 09-04-2019

**Due on : 25-04-2019 by 1:00 PM IST**

Please send your offer in sealed envelope specifying Enquiry No, Date & Due Date,  
ALONG WITH your credentials for the following items:

#### Important Note:

Please note that e-mail quotations are not acceptable however you may send your  
queries (if any) to [localpurchase@ipr.res.in](mailto:localpurchase@ipr.res.in)

Please ensure your sealed quotation reaches this office not later than above mentioned  
due date and time.

Kindly go through the following documents properly before quoting which are available on  
the IPR web portal i.e., [http://www.ipr.res.in/documents/tender\\_terms.html](http://www.ipr.res.in/documents/tender_terms.html) / attached  
herewith.

- 1) Instructions to the bidders & Terms and conditions (refer Form No: **IPR-LP-01.V4**)
- 2) Bidding format

**GST for Goods and Services (IGST/CGST/SGST TAX BENEFITS):** Please refer **clause no: 8** of Form No: **IPR-LP-01.V4**

#### QUOTATION SHOULD BE ADDRESSED TO PURCHASE OFFICER ONLY

Sr No	Description	Quantity
1	Integrated chip OPA2132U, High speed FET- input operational amplifier, Package-8 lead SOIC, TI make	300.0 Nos.
2	Integrated chip HCPL2530, Dual channel High Speed Optocoupler, Package- 8 pin PDIP, ON semiconductor /Fairchild make	150.0 Nos.

3	Integrated chip OPA404KU , Quad High-Speed Precision Difet OPERATIONAL AMPLIFIER , 16 pin SOIC Double Width Package-16 , TI make	20.0 Nos.
4	Integrated chip RAM CY62167DV30LL-55ZXI, SRAM, 16Mb ,3V 55ns ,1M x 16 , Package-TSOP-48, Cypress Semiconductor make	25.0 Nos.
5	Integrated chip SN74LVCH162244AGR, 16-Bit Buffer/Driver with 3-State Outputs, Package- TSSOP-48, TI make	50.0 Nos.
6	Integrated chip 74LVX3245MTC, Bus Transceivers with three state output, Package- TSSOP-24 , ON semiconductor / Fairchild make	100.0 Nos.
7	Integrated chip HA9P5320-5Z, 1µS precision sample and hold amplifier, Package- 16 pin SOIC-Wide, Intersil / Renesas Electronics make	25.0 Nos.
8	Integrated chip , THS4140IDGN ,HIGH-SPEED FULLY DIFFERENTIAL I/O AMPLIFIERS, Package-8 PIN MSOP PowerPAD, TI make	400.0 Nos.

Note: Notice: After Purchase order placement the party should deliver the material with proper antistatic packaging. Without antistatic package material will not be accepted.

TDS as per CGST Act: As per provisions of section No. 51 of the CGST Act 2017, TDS @2% (IGST 2% or CGST 1% and SGST 1%) will be deducted while making payment to the suppliers where total value of orders/contracts/work orders exceeds Rs. 2.5 lakhs, in the event of order in Indian Rupees. Necessary TDS Certificate will be issued to the supplier after TDS deduction.

Encl: As Per Attachment

Sd/-

Mr. D. Ramesh  
Purchase Officer-II

**Information to Vendors:** We are working towards a single platform for our future requirement. Hence, please refer IPR website i.e, <http://www.ipr.res.in/documents/tenderseng.html> for our future requirement.

Compliance Form

Sr.No.	Particulars	IPR Requirement	Vendor's Specification
1.	Integrated chip	Integrated chip OPA2132U, High speed FET- input operational amplifier, Package-8 lead SOIC, TI make	
2.	Integrated chip	Integrated chip HCPL2530, Dual channel High Speed Optocoupler, Package- 8 pin PDIP, ON semiconductor /Fairchild	
3.	Integrated chip	Integrated chip OPA404KU , Quad High- Speed Precision Difet OPERATIONAL AMPLIFIER , 16 pin SOIC Double Width Package- 16 , TI make	
4.	Integrated chip	Integrated chip RAM CY62167DV30LL-55ZXI, SRAM, 16Mb ,3V 55ns ,1M x 16 , Package-TSOP-48, Cypress Semiconductor make	
5.	Integrated chip	Integrated chip SN74LVCH162244AGR, 16-Bit Buffer/Driver with 3-State Outputs, Package- TSSOP-48, TI make	
6.	Integrated chip	Integrated chip 74LVX3245MTC, Bus Transceivers with three state output, Package- TSSOP-24 , ON	

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		semiconductor / Fairchild make	
7.	Integrated chip	Integrated chip HA9P5320-5Z, 1 $\mu$ S precision sample and hold amplifier, Package- 16 pin SOIC-Wide, Intersil / Renesas Electronics make	
8.	Integrated chip	Integrated chip THS4140IDGN ,HIGH- SPEED FULLY DIFFERENTIAL I/O AMPLIFIERS, Package - 8 PIN MSOP Power PAD, TI make	

Bidder's Sign with Official Stamp